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Attorney Docket Number

KOY-16174

|   |   | Application Number | 10540592   |      |  |
|---|---|--------------------|------------|------|--|
|   |   | Filing Date        | 2005-07-15 |      |  |
| INFORMATION DISCLOSURE                  | First Named Inventor Hiros                                    |                    | hi Harada  |      |  |
|   | STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99) | Art Unit           |            | 1794 |  |
| (Not for submission under 57 of K 1.55) | Examiner Name   | Thuy               | Tran Lien  |      |  |

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| Notice submission under or or K 1.55)                        | Examiner Name        | Thuy   | Tran Lien  |  |
|  | Attorney Docket Numb | er     | KOY-16174  |  |

| /LT/  | /LT/ 1 English translation of Claim 1 of JP H50-157548 A. |  |  |  |  |  |  |
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